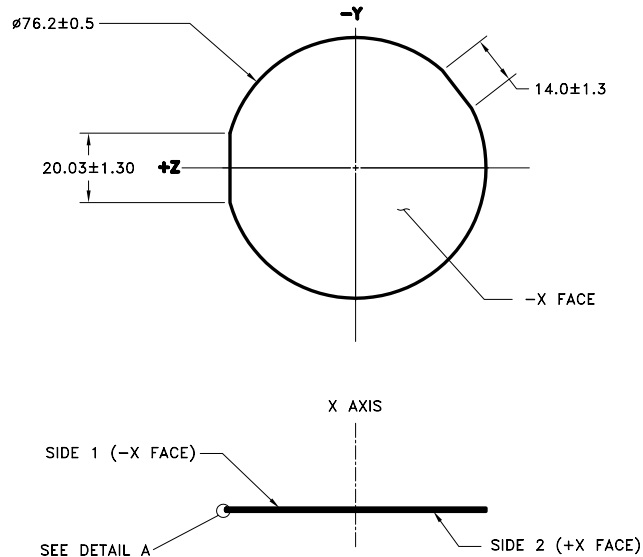


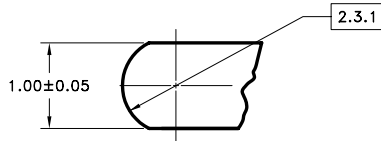
NOTES:

- 1.0.0 ORIENTATIONS
- 1.1.0 WAFER SURFACE IS NORMAL TO X AXIS WITHIN $\pm 0.5^\circ$.
- 1.2.0 WAFER FLAT
- 1.2.1 PRIMARY FLAT, PERPENDICULAR TO THE +Z AXIS $\pm 0.5^\circ$
- 1.2.2 SECONDARY FLAT 135° CLOCKWISE FROM THE PRIMARY FLAT WHEN VIEWING THE -X POLISHED FACE.
- 2.0.0 SURFACES
- 2.1.0 SIDE 1
- 2.1.1 POLISHED, NO PITS OR SCRATCHES ALLOWED WITHIN THE WORKING AREA (ENTIRE WAFER DIAMETER LESS 1.0MM AROUND THE EDGE). INSPECTED USING UNAIDED EYE WITH REFLECTED LIGHT.
- 2.2.0 SIDE 2
- 2.2.1 GROUND. Ra 0.5um - 0.7um.
- 2.3.0 EDGE
- 2.3.1 ALL EDGES ROUNDED WITH A R=0.70 \pm 0.08 RADIUS.
- 2.3.2 NO CHIPS GREATER THAN 0.5mm IN PENETRATION AND 1.0mm IN LENGTH.
- 2.4.0 FLATNESS
- 2.4.1 WARP \leq 50um. MEASURED IN THE FREE STATE.
- 2.4.2 T.T.V < 10.0um. DEFINED AS THE DIFFERENCE BETWEEN THE LOWEST AND HIGHEST ELEVATION OF THE WAFER, MEASURED IN THE CLAMPED STATE.

REVISIONS					
ZONE	REV	DESCRIPTION	ECO NO	APPD.	DATE
ALL	D	UPDATE PER EO	9610	SR	12/15/97



For Reference Only



DETAIL A
SCALE: 25X

FINISH: SEE NOTES		CONTRACT NUMBER		Crystal Technology, Inc. A Siemens Company
MATERIAL: LN		DR. RATZLIFF 12/15/97		
SPEC. NO.		CHK.		TITLE: LN WAFER, 76.2 ϕ X1.0 (X) POL/GRD 20.0 +Z FLT 14.0 SEC
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM		APPD.		
TOLERANCES		DESIGN ACTIVITY APPROVAL:		SIZE: A
INCHES	MILLIMETERS	CUSTOMER APPROVAL:		DWG. NO. 97-00663-01
.XX \pm .01	X.XX \pm 0.25			REV. D
.XXX \pm .005	X.XXX \pm 0.125	DO NOT SCALE DRAWING		SCALE: N/A
.XXXX \pm .0020				SH. 1 OF 1
ANG \pm 5'				

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